

#### **Description**

The AP6N40D is silicon N-channel Enhanced

VDMOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.



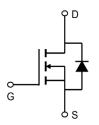
V<sub>DS</sub> = 400V I<sub>D</sub> =6A

 $R_{DS(ON)} < 1.0\Omega$  @  $V_{GS}=10V$  (Type:  $0.8\Omega$ )

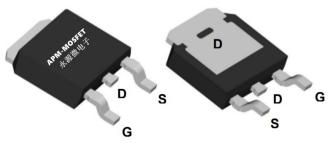


Uninterruptible Power Supply(UPS)

Power Factor Correction (PFC)







Package Marking and Ordering Information

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Product ID	Pack	Marking	Qty(PCS)		
AP6N40D	TO-252-3L	AP6N40D XXX YYYY	2500		

### Absolute Maximum Ratings (T<sub>c</sub>=25°Cunless otherwise noted)

Symbol	Parameter	Value	Unit
VDSS	Drain-Source Voltage (V <sub>GS</sub> = 0V)	400	V
ID	Continuous Drain Current	6	Α
IDM	Pulsed Drain Current (note1)	28	Α
VGS	Gate-Source Voltage	±30	V
Eas	Single Pulse Avalanche Energy (note2)	176	mJ
IAR	Avalanche Current (note1)	7	Α
Ear	Repetitive Avalanche Energy note1)	18	mJ
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)	32.9	W
TJ, Tstg	Operating Junction and Storage Temperature Range	-55~+150	°C
RthJC	Thermal Resistance, Junction-to-Case	3.8	°C/W
RthJA	Thermal Resistance, Junction-to-Ambient	13.3	°C/W





#### Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

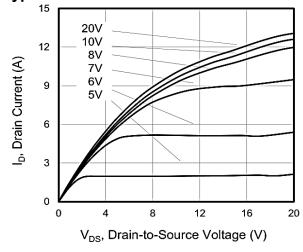
Symbol	Parameter Test Conditions		Min	Тур	Max	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	400	440		V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V, T <sub>J</sub> =25°C			1	μA
IGSS	Gate-Source Leakage	V <sub>GS</sub> = ±30V			±100	nA
VGS(th)	Gate-Source Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.0	3.5	4.0	V
RDS(on)	Drain-Source On-Resistance (Note3)	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.5A		0.8	1.0	Ω
C <sub>iss</sub>	Input Capacitance			700		
Coss	Output Capacitance	$V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz$		94		pF
Crss	Reverse Transfer Capacitance			12		
Qg	Total Gate Charge			19		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DD</sub> =520V, I <sub>D</sub> = 7A, V <sub>GS</sub> = 10V		3.7		nC
$Q_{\mathrm{gd}}$	Gate-Drain Charge			11		
td(on)	Turn-on Delay Time			13		
tr	Turn-on Rise Time	V 205V L 7A D 250		20		
td(off)	Turn-off Delay Time	$V_{DD}$ =325V, $I_D$ = 7A, $R_G$ = 25 $\Omega$		76		ns
t <sub>f</sub>	Turn-off Fall Time			40		
IS	Continuous Body Diode Current	T <sub>C</sub> = 25 °C			7.0	Α
ISM	Pulsed Diode Forward Current	10-25 0			28	Α
V <sub>SD</sub>	Body Diode Voltage	$T_J = 25^{\circ}C$ , $I_{SD} = 7A$ , $V_{GS} = 0V$			1.4	V
trr	Reverse Recovery Time	V <sub>GS</sub> = 0V,I <sub>S</sub> = 7A, di <sub>F</sub> /dt =100A		260		ns
Qrr	Reverse Recovery Charge	/µs		3.8		μC

#### Note:

- $1\$  The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The EAS data shows Max. rating . IAS = 4.5A, VDD = 50V, RG = 25  $\Omega$ , Starting TJ = 25  $^{\circ}$ C
- 3、The test condition is Pulse Test: Pulse width ≤  $300\mu$ s, Duty Cycle ≤ 1%
- 4. The power dissipation is limited by 150  $^\circ\!\mathrm{C}$  junction temperature
- 5、The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



### **Typical Characteristics**



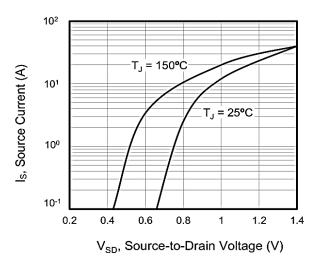


Figure 1. Output Characteristics (T J = 25°C)

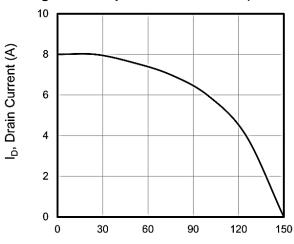
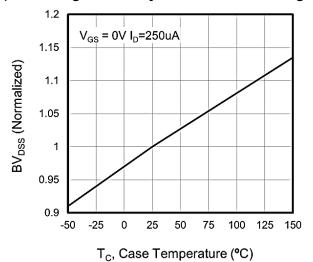
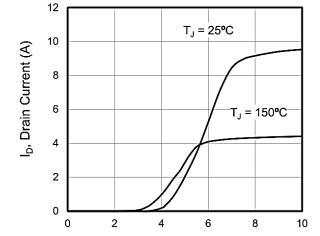


Figure 2. Body Diode Forward Voltage



T<sub>C</sub>, Case Temperature (A) Figure 3. Drain Current vs. Temperature



V<sub>GS</sub>, Gate-to-Source Voltage (V)

Figure 5. Transfer Characteristics

Figure 4. BV DSS Variation vs. Temperature

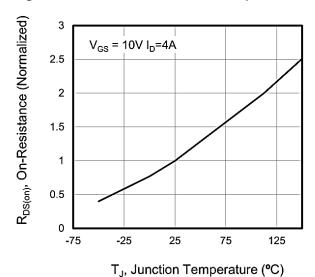
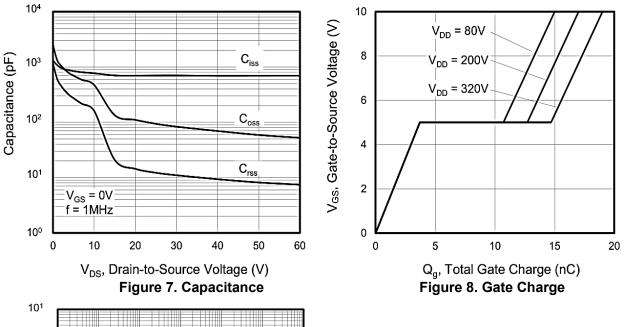


Figure 6. On-Resistance vs. Temperature



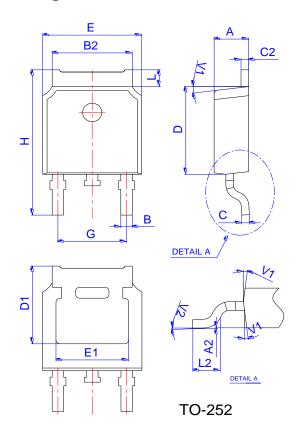


Z<sub>thJC</sub>, Thermal Impedance (K/W) 10º 10-1 D = 0.5D = 0.2D = 0.1D = 0.0510-2 D = 0.02D = 0.01Single Pulse 10-3 10-6 10-5 10-4 10-3 10-2 10-1 10-7 T<sub>p</sub>, Pulse Width (s)

Figure 9. Transient Thermal Impedance

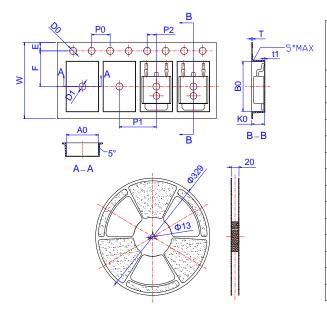


# Package Mechanical Data: TO-252-3L



	Dimensions					
Ref.	Millimeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF		0.209REF			
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

# **Reel Spectification-TO-252**



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
Е	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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Edition	Date	Change
Rve1.0	2021/1/31	Initial release

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